

**SECTION I**  
**LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

<b>MANUFACTURER INFORMATION:</b> <b>TTM Technologies (Santa Clara)</b> 407 Mathew Street, Santa Clara, CA, 95050 US	<b>PLANT LOCATION:</b> Same Address as Manufacturer	<b>CAGE Code:</b> 65916 <b>Phone:</b> 408-486-3184 <b>Fax:</b> 408-727-1003 <b>E-Mail:</b>
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**CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2  
 Qualification Letters: VQE-17-030872  
 Rigid Base Material: GM: Glass Base, Woven, Triazine and/or Bismaleimide Modified Epoxy Resin, Flame Resistant  
 Max. Panel Size: 18.5" x 24.5"  
 Max. Number of Layers: 10  
 Max. Board Thickness: .079"  
 Min. Hole Size: .023" Drilled Plated-Through Hole Before Plating  
 Aspect Ratio: 2:1 Through-Hole  
 Min. Conductor Width/Space: .02"/.007"  
 Hole Preparation: Plasma Desmear  
 Hole Wall Conductive Coating: Electroless Copper  
 Copper Plating: Direct Current Plate  
 Solder Resist: Liquid Photoimageable  
 Finish System: Hot Oil Reflow of Plated Sn/Pb  
 Additional Fab Capabilities: Foil Lamination

**CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2  
 Qualification Letters: VQE-03-003888, VQE-10-020500, VQE-10-020581, VQE-11-022973, VQE-14-028240, VQE-14-028262, VQE-15-029137, VQE-15-029683, VQE-16-030610  
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant  
 Max. Panel Size: 21.5" x 24.5"  
 Max. Number of Layers: 28  
 Max. Board Thickness: .19"  
 Min. Hole Size: .0098" Drilled Plated-Through Hole Before Plating  
 Aspect Ratio: 11:1 Through-Hole  
 Min. Conductor Width/Space: .004"/.004"  
 Hole Preparation: Plasma Desmear, Plasma Etchback  
 Hole Wall Conductive Coating: Electroless Copper  
 Copper Plating: Direct Current Plate  
 Hole Fill/Via Plug: Conductive, Non-Conductive  
 Solder Resist: Liquid Photoimageable  
 Finish System: ENIG, Electrolytic Ni (no Au), HASL, Hot Oil Reflow of Plated Sn/Pb  
 Additional Fab Capabilities: Blind Vias, Foil Lamination  
 Controlled Impedance: Differential, Single-Ended

**CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2  
 Qualification Letters: VQE-03-003888, VQE-10-020500, VQE-10-020581, VQE-11-022973, VQE-14-028240, VQE-14-028262, VQE-16-030610  
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant  
 Max. Panel Size: 18" x 24"  
 Max. Number of Layers: 33  
 Max. Board Thickness: .19"  
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating  
 Aspect Ratio: 9:1 Through-Hole  
 Min. Conductor Width/Space: .004"/.004"  
 Hole Preparation: Plasma Desmear, Plasma Etchback  
 Hole Wall Conductive Coating: Electroless Copper  
 Copper Plating: Direct Current Plate  
 Hole Fill/Via Plug: Conductive, Non-Conductive  
 Solder Resist: Liquid Photoimageable  
 Finish System: ENIG, Electrolytic Ni (no Au), HASL, Hot Oil Reflow of Plated Sn/Pb  
 Additional Fab Capabilities: Blind Vias, Foil Lamination, Sequential Lamination  
 Controlled Impedance: Differential, Single-Ended

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**CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION**

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4  
 Qualification Letters: VQE-03-003895, VQE-10-020500, VQE-10-020581, VQE-11-022973, VQE-14-028240, VQE-14-028262, VQE-16-030610  
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant  
 Flex Base Material: Copper Clad Adhesiveless Polyimide  
 Max. Panel Size: 18" x 24"  
 Max. Number of Layers: 16  
 Max. Board Thickness: .12"  
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating  
 Aspect Ratio: 9:1 Through-Hole  
 Min. Conductor Width/Space: .004"/.004"  
 Hole Preparation: Plasma Desmear, Plasma Etchback  
 Hole Wall Conductive Coating: Electroless Copper  
 Copper Plating: Direct Current Plate  
 Hole Fill/Via Plug: Conductive  
 Solder Resist: Liquid Photoimageable  
 Finish System: ENIG, Electrolytic Ni (no Au), HASL, Hot Oil Reflow of Plated Sn/Pb  
 Additional Fab Capabilities: Sequential Lamination  
 Controlled Impedance: Differential, Single-Ended  
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

**CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION**

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4  
 Qualification Letters: VQE-03-003895, VQE-10-020500, VQE-10-020581, VQE-11-022973, VQE-14-028240, VQE-16-030610  
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant  
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive  
 Max. Panel Size: 18" x 24"  
 Max. Number of Layers: 6  
 Max. Board Thickness: .043"  
 Min. Hole Size: .031" Drilled Plated-Through Hole Before Plating  
 Aspect Ratio: 1:1 Through-Hole  
 Min. Conductor Width/Space: .004"/.004"  
 Hole Preparation: Plasma Desmear, Plasma Etchback  
 Hole Wall Conductive Coating: Electroless Copper  
 Copper Plating: Direct Current Plate  
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb  
 Flex Usage: Use A (Flex During Installation), Use B (Dynamic Flex)

**CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2  
 Qualification Letters: VQE-07-013211, VQE-11-022973, VQE-14-028240, VQE-14-028262, VQE-16-030611, VQE-17-030871  
 Composition: H - Homogenous thermoplastic base material printed boards, M - Mixed based material printed boards  
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; Woven Glass Reinforced, Hydrocarbon Resin with Ceramic Fill  
 Max. Panel Size: 18" x 24"  
 Max. Number of Layers: 10  
 Max. Board Thickness: .109"  
 Min. Hole Size: .0118" Drilled Plated-Through Hole Before Plating  
 Aspect Ratio: 9:1 Through-Hole  
 Min. Conductor Width/Space: .004"/.004"  
 Hole Preparation: Permanganate Etchback, Plasma Desmear  
 Hole Wall Conductive Coating: Electroless Copper  
 Copper Plating: Direct Current Plate  
 Hole Fill/Via Plug: Conductive, Non-Conductive  
 Solder Resist: Liquid Photoimageable  
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb  
 Additional Fab Capabilities: Blind Vias, Sequential Lamination  
 Controlled Impedance: Differential, Single-Ended

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**CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2  
 Qualification Letters: VQE-03-003888, VQE-10-020500, VQE-10-020581, VQE-11-022973, VQE-14-028240, VQE-14-028262, VQE-16-030610  
 Rigid Base Material: BI: Aramid Fabric, Nonwoven, Polyimide Resin  
 Max. Panel Size: 18" x 24"  
 Max. Number of Layers: 14  
 Max. Board Thickness: .12"  
 Min. Hole Size: .012" Drilled Plated-Through Hole Before Plating  
 Aspect Ratio: 6.45:1 Through-Hole  
 Min. Conductor Width/Space: .004"/.004"  
 Hole Preparation: Plasma Desmear, Plasma Etchback  
 Hole Wall Conductive Coating: Electroless Copper  
 Copper Plating: Direct Current Plate  
 Hole Fill/Via Plug: Conductive  
 Solder Resist: Liquid Photoimageable  
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb

**CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2  
 Qualification Letters: VQE-13-026953, VQE-14-028262, VQE-17-030872  
 Rigid Base Material: BF: Aramid Fabric, Nonwoven, Epoxy Resin  
 Max. Panel Size: 18" x 24"  
 Max. Number of Layers: 14  
 Max. Board Thickness: .076"  
 Min. Hole Size: .0118" Drilled Plated-Through Hole Before Plating  
 Aspect Ratio: 7:1 Through-Hole  
 Min. Conductor Width/Space: .0088"/.008"  
 Hole Preparation: Plasma Desmear, Plasma Etchback  
 Hole Wall Conductive Coating: Electroless Copper  
 Copper Plating: Direct Current Plate  
 Hole Fill/Via Plug: Conductive  
 Solder Resist: Liquid Photoimageable  
 Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb  
 Controlled Impedance: Differential